



DDR4 DIMM

TE Internal #: 2309413-3

SO DIMM Sockets, Small Outline (SO), Stack Height .362 in [9.2 mm], Right Angle Module Orientation, 260 Position, .02 in [.5 mm]

Centerline, DDR4 DIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: **Small Outline (SO)**

Stack Height: **9.2 mm [.362 in]**

Module Orientation: **Right Angle**

Number of Positions: **260**

Centerline (Pitch): **.5 mm [.02 in]**

[All DDR4 SO DIMM Sockets \(39\)](#)

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector System | Cable-to-Board |
| Connector & Contact Terminates To | Printed Circuit Board |
| DRAM Type | Small Outline (SO) |

Configuration Features

| | |
|---------------------|-------------|
| Number of Keys | 1 |
| Number of Rows | 2 |
| Module Orientation | Right Angle |
| Number of Positions | 260 |

Electrical Characteristics

| | |
|--------------|-------|
| DRAM Voltage | 1.2 V |
|--------------|-------|

Signal Characteristics

| | |
|---------------|-------|
| SGRAM Voltage | 1.2 V |
|---------------|-------|

Body Features

| | |
|-------------------------|-----------------|
| Ejector Location | Both Ends |
| Retention Post Material | Stainless Steel |



| | |
|-------------------------|--------------------------------|
| Latch Material | High Temperature Thermoplastic |
| Retention Post Location | Both Ends |
| Module Key Type | Offset Left |
| Ejector Type | Locking |
| Connector Profile | High |

Contact Features

| | |
|--|---|
| Memory Socket Type | Memory Card |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Base Material | Copper Alloy |
| Contact Current Rating (Max) | .5 A |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .254 μm [10 μin] |

Termination Features

| | |
|---|---------------|
| Insertion Style | Cam-In |
| Termination Method to Printed Circuit Board | Surface Mount |

Mechanical Attachment

| | |
|--------------------------|-----------------|
| Mating Alignment Type | Standard Keying |
| PCB Mount Retention | With |
| PCB Mount Retention Type | Solder Peg |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|--------------------------------|
| Housing Material | High Temperature Thermoplastic |
| Housing Color | Black |
| Centerline (Pitch) | .5 mm[.02 in] |

Dimensions

| | |
|--------------------|-----------------|
| Stack Height | 9.2 mm[.362 in] |
| Row-to-Row Spacing | 8.2 mm[.322 in] |

Usage Conditions

| | |
|-----------------------------|---------------------------|
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
|-----------------------------|---------------------------|

Operation/Application

| | |
|---------------------|-------|
| Circuit Application | Power |
|---------------------|-------|



Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

| | |
|--------------------|-------------|
| Packaging Quantity | 500 |
| Packaging Method | Tape & Reel |

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

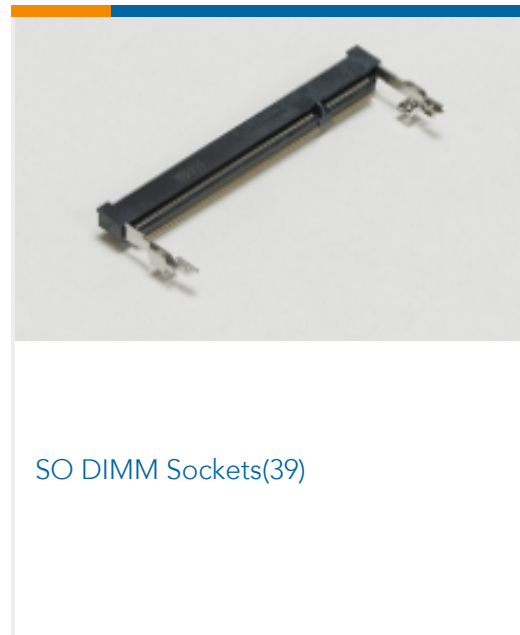
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | DDR4 DIMM



Customers Also Bought





Documents

Product Drawings

[DDR4 SODIMM 260P 9.2H STD](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2309413-3_1.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309413-3_1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309413-3_1.3d_stp.zip](#)

English

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Product Specifications

[Application Specification](#)

English